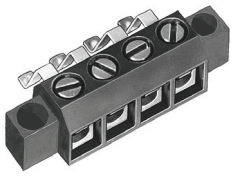
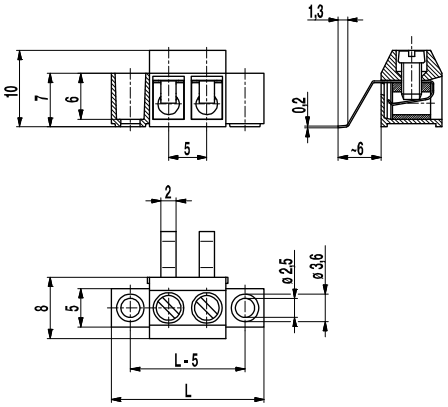
PCB connector for SMD

950-A-SMD

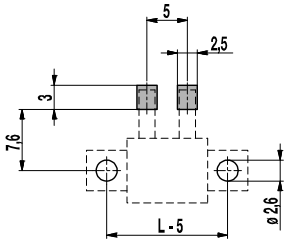
Screw connection, with solder tags





L = No. of poles x pitch + 10 mm

PCB Layout



Solder paste thickness: 0,15 - 0,2 mm

Screw connections with wire protection are used on versions 950-A-SMD with a pitch of 5 mm.
This wire protection is extended beyond the rear panel of the housing and bent downwards for connection to the soldering pads. When the terminal strip is fitted, the preloaded soldering tags push against the soldering pads. This assures current transfer with high contact stability.
The housings have mounting flanges at either side, for reliable mechanical fastening on the circuit board. This terminals are packed in tube magazines.

Part Numbers

No. of poles	950-A-SMD	Length	Pcs
2	20.871.266	20,00	624
3	20.871.267	25,00	504
4	20.871.268	30,00	408
5	20.871.269	35,00	360
6	20.871.270	40,00	312
7	20.871.271	45,00	264
8	20.871.272	50,00	240
9	20.871.273	55,00	216
10	20.871.274	60,00	192
11	20.871.275	65,00	192
12	20.871.276	70,00	168

General Information

Pitch	5 mm
No. of poles	2 - 12

Technical Data

Clamping Range	*solid / flexible / AWG*
	0,34 - 2,5 mm² / 0,34 - 2,5 mm² / 22 - 14 AWG
Rated Cross Section	1,5 mm²
Wire Stripping Length	6 mm
Overvoltage Category	III
Pollution Severity Level	3
Rated Voltage	125 V
Rated Impulse Voltage	2,5 kV
Rated Insulation Voltage	130 V acc. to EN 60998-1
Rated Current	6 A
Soldering process	Reflow solder
Torque	0,4 Nm

Material

Moulding	PA, black, V-0
Comparative Tracking Index	CTI 250
Insulating Group	IIIa
Temperature Range	-40°C up to 105°C; reflow solder temperature (Peak) max. 250°C (15-30 s)
Terminal body	Nickel plated brass
Screw	M2,6; zinc plated steel, blue passivated
Wire protector	Tin plated tin bronze

Approvals

	Current	Voltage	Group	AWG	Nm
	15	300	B	26 - 14	0,4
	15	300	B	26 - 14	0,4

Options / Accessories

- Consecutive numbering
- Special marking according to drawing
- Self-adhesive marking strip BST-5,00 [1]
- Tape-on-Reel on request

[1] To be fitted after reflow soldering process